

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test | | User Part Number HPZR-C13-Q Part Description | | | | | | | | | | | |
|--|--|---|-----------------------------------|--------------|------------|-----------|-----------|-----------|---------------|-------|--|--|--|
| | | | | | | | | | Nexperia DHAM | Zener | | | |
| | | | | | | | | | SMD package | | | | |
| | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | | | | | | | |
| | | | TEST Pre- and Post-Stress | | | | | | | | | | |
| | | # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | | | | | |
| # A1 | PC Preconditioning | JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering | 24 hours 168 hours 3 cycles | 1514 | 64430 | 0 | | | | | | | |
| # B1 | HTRB | MIL-STD-750-1 M1038 Method A Tj = Tjmax, VR = 80 % of rated reverse voltage | 1000 hours | 250 | 11400 | 0 | | | | | | | |
| # B1b | SSOP Steady State Operational | MIL-STD-750-1 M1038 Method B Tj = Tjmax, Iz = 100% of max. datasheet reverse current | 1000 hours | 44 | 1920 | 0 | | | | | | | |
| # A4 | TC Temperature Cycling | JESD22-A104 -65 °C to Tjmax, not to exceed 150°C | 1000 cycles | 311 | 14080 | 0 | | | | | | | |
| # A3 or | UHAST Unbiased HAST | JESD22-A118 Tamb = 130 °C, RH = 85 % JESD22-A102 Tamb = 121 °C, RH = 100 % | —96 hours | 311 | 14080 | 0 | | | | | | | |
| # A3 alt | Autoclave | Pressure = 205 kPa (29.7 psia) | | | | | | | | | | | |
| # A2 alb | H3TRB High Humidity High Temperature Reverse Bias | JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of | 1000 have- | 211 | 14000 | 0 | | | | | | | |
| # A2 alt | IOL | MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = | 1000 hours | 311 | 14080 | 0 | | | | | | | |
| # A5 | Intermittent Operating Life | 100 °C for 15000 cycles | 1000 hours | 312 | 14120 | 0 | | | | | | | |
| # C8 | RSH Resistance to Solder Heat | JESD22-A111 260 °C ± 5 °C | 10 s | 269 | 8070 | 0 | | | | | | | |
| # C10 | SD Solderability | J-STD-002 | | 19 | 6660 | 0 | | | | | | | |

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia | | | | | |
| DHAM | Zener | 11400 | 0 | 0,37 | 2,68E+09 |

© 2024 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com